

1 Abstract of the Disclosure

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3 The present invention relates to a heat sink (1) with a main body (2) for
4 accommodating at least one electronic structural element (5), and with a spring
5 element (3) for pressing the structural element (5) against the main body (2),
6 whereby the spring element (3) is held on the main body (2) by a connecting
7 means. It is provided that the connecting means are configured as a push-on
8 connection (15) and have a projection (7) on the main body (2) and a mounting
9 opening (14) in the spring element (3) for the projection (7), whereby the opening
10 edge (23) of the mounting opening (14) bears, at least in sections, against the
11 lateral surface of the projection (7) under preload resulting from the intrinsic
12 elasticity of the spring element (3) and/or the projection (7).

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14 (Figure 3)